

SPECIFICATION

EXPOSURE METHOD AND EXPOSURE APPARATUS

This application is a Continuation of PCT/JPOI/11635 filed 12/18/

BACKGROUND OF THE INVENTION

1. Field of the Invention

The present invention relates to an exposure method and exposure apparatus for transferring a mask pattern onto a photosensitive substrate in an exposure body section. In particular, the present invention relates to the control of an exposure method and exposure apparatus when an error occurs in an air-conditioning system or temperature control system.

2. Description of Related Art

Exposure apparatuses used in a photolithography step in the manufacture of electronic devices such as semiconductor devices (e.g., integrated circuits) and liquid crystal displays are installed inside a clean room. However, because a purified environment is necessary, the exposure body section (which includes the apparatus body and the like described below), in particular, is installed inside a chamber such as an environmental chamber. An air-conditioning system is provided in the chamber, so that temperature control is performed inside the chamber. In addition, the air-conditioning system enables the air in the chamber to be purified by the use of filters such as high efficiency particle air (HEPA) filters and chemical filters and the like.

In many cases, at least a portion of a control system (i.e., a control unit) that performs the control of each section of the exposure body section that carries out exposure processing (i.e., performs movement control of movable sections such as a stage, controls exposure conditions, controls transporting systems such as those for the mask and photosensitive substrate (i.e., substrates such as wafers and glass plates on whose surface photoresist has been coated - referred to below simply as "wafers"), and performs other control) and also supplies power and the like is mounted integrally inside a chamber that houses the apparatus main body, or is located close to the apparatus main body. In